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YASUTAKE YASUTAKA(54) BOARD FOR CONSTRUCTION MATERIALS AND ITS MANUFACTURING  
METHOD

(57)Abstract:

PROBLEM TO BE SOLVED: To industrially advantageously provide a construction material board wherein last fiber plants belonging to Malvaceae or Tiliaceae is used as raw material, an emission amount of formaldehyde is E0 type, durability of a germ preventive, insect repellent and termite preventive effect is high and physical properties are excellent.

SOLUTION: A urea resin wood adhesive wherein free formaldehyde is  $\leq 0.5$  wt.% and a viscosity is 0.1 to 0.3 Pa.S and at least one kind of a germ preventive agent, an insect repellent agent and a termite preventive agent are dispersed in a pulverized material of last fiber plants belonging to Malvaceae or Tiliaceae, and after molding, the product is heated and pressurized to prepare the board for construction materials.

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CLAIMS

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## [Claim(s)]

[Claim 1] The board for building materials characterized by distributing at least one sort of the urea resin wood adhesives whose isolation formaldehyde is 0.5 or less % of the weight, and whose viscosity is 0.1-0.3Pa.S, an antimicrobial agent and an insecticide, and an anti-ant agent, carrying out heating pressurization after molding and growing into the grinding object of the bast fiber vegetation belonging to Malvaceae or Tiliaceae.

[Claim 2] The board for building materials according to claim 1 whose principal components of the aforementioned antimicrobial agent, an insecticide, and an anti-ant agent are an organic iodine compound and organic nitrogen compounds.

[Claim 3] Said organic iodine compound is a 3-iodine-2-propynyl butyl carver mate, and said organic nitrogen compounds are 1-[(6-chloro-3-pyridyl JINRU) methyl]-4 and 5-dihydro. - Board for building materials according to claim 2 which is an N-nitro-1H-imidazole-2-amine.

[Claim 4] The board for building materials according to claim 1 which is the grinding object with which the grinding object of the bast fiber vegetation belonging to said Malvaceae uses a kenaf core part as a principal member.

[Claim 5] The board for building materials according to claim 1 which is the grinding object with which the grinding object of the bast fiber vegetation belonging to said Tiliaceae uses a jute core part as a principal member.

[Claim 6] The urea resin wood adhesives whose process and \*\* isolation formaldehyde which grind the bast fiber vegetation belonging to \*\* Malvaceae or Tiliaceae in manufacture of the board for building materials are 0.5 or less % of the weight and whose viscosity is 0.1-0.3Pa.S, The manufacture approach of the board for building materials characterized by \*\*\*\*\* which casts the process which distributes at least one sort of an antimicrobial agent, an insecticide, and an anti-ant agent in said grinding object, and the grinding object of \*\* above by which distributed processing was carried out in the shape of a board, and is given to the process which carries out heating pressurization.

[Claim 7] The manufacture approach of the board for building materials according to claim 6 of establishing the separation process for \*\*\*\*ing a bast fiber section content to 10 or less % of the weight, and using a core part as a principal member after said grinding process.

[Claim 8] The manufacture approach of the board for building materials according to claim 6 that the F/U mole ratio of formaldehyde (F) and a urea (U) performs the last methylol-ization in 1.03-1.07, and said urea resin wood adhesives are prepared.

[Claim 9] The manufacture approach of the board for building materials according to claim 6 which the gelation time in 60 degrees C of said urea resin wood adhesives is for 60 - 90 minutes, and distributes the adhesives concerned in said grinding object in front of the gelation time.

[Claim 10] The manufacture approach of the board for building materials according to claim 6 that the conditions of the aforementioned heating pressurization are 125-135 degrees C and 15-25kg/cm2.

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